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(54) **INPUT DEVICE SECURING TECHNIQUES**

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This patent is subject to a terminal dis-
claimer.

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(57) **ABSTRACT**

Input device adhesive techniques are described. A pressure
sensitive key includes a sensor substrate having one or more
conductors, a spacer layer, and a flexible contact layer. The
spacer layer is disposed proximal to the sensor substrate and
has at least one opening. The flexible contact layer is spaced
apart from the sensor substrate by the spacer layer and
configured to flex through the opening in response to an
applied pressure to initiate an input. The flexible contact
layer is secured to the spacer layer such that at first edge, the
flexible contact layer is secured to the spacer layer at an
approximate midpoint of the first edge and is not secured to
the spacer along another portion of the first edge and at a
second edge, the flexible contact layer is not secured to the

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